ACCRETECH | TOKYO SEIMITSU

Earnings Conference for FY2027/3 2Q

2026/11/04

TOKYO SEIMITSU CO., LTD.

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- **Cautionary Statement with respect to Forward-Looking Statements：** This presentation data and information verbally provided contain “forward-looking statements” that are based on current best available information and policies. There are various factors such as world economic conditions and semiconductor/automobile market conditions which will directly and indirectly impact the Company’s results in the future. As a result, future outcomes may differ from those projected in this presentation.
- **Wordings and Data in presentation :** Unless otherwise noted, “SPE” denotes our Semiconductor Production Equip. Segment, “Metrology (or Metr.)” denotes our Metrology Equip.Segment, “Net profit” denotes Net profit attributable to owner of the parent, and “MTP” denotes Mid-Term business Plan.
- **About data:** Information listed in this presentation is summarized in Billions of Yen (BJPY or B) or percentage except as otherwise noted. As a result, there may be a case where the total of individual amount and total amounts in each matter may differ.
- **Audit procedure:** This presentation is not subject to audit procedures.
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Executive Summary

FY2027/3 1H/2Q Results	• Company-wide sales, all profits, and orders each reached new fiscal-half and quarterly highs • Strong demand continues, particularly for SPE
FY2027/3 Forecast	• FY Forecasts raised (Sales: ¥189.0B => ¥192.0B; OP ¥44.0B => ¥45.0B) • Both sales and OP expected to meet MTP quantitative targets • Dividend projection updated following the Revision of forecasts (¥304 per share => ¥316 per share)
Outlook for FY2028/3 and Beyond	• Our equipment's market to continue expanding through at least CY2028 • Aim to double our Prober production capacity by mid-FY2028 • Continue to monitor component constraint risks closely

FY2027/3 First Half (1H) Results

Orders, Sales, and all profits reached new half-year highs. Orders for SPE exceeded 100.0BJPY

Company-Wide results (BJPY)	FY2026/3 1H	FY2026/3 2H	FY2027/3 1H	HoH	YoY
Orders	80.6	82.5	**139.0**	+69%	+72%
Sales	77.1	89.8	**92.4**	+3%	+20%
Operating profit (OP)	14.7	19.0	**20.3**	+7%	+38%
(OP Margin) (OPM)	(19.1%)	(21.2%)	**(22.0%)**	+0.8pt	+2.9pt
Recurring profit	15.0	19.8	**21.1**	+7%	+41%
Net profit	9.6	15.1	**15.5**	+2%	+61%
R&D	5.5	6.5	**6.8**	+4%	+22%
Capex	6.9	4.2	**4.7**	+13%	-32%
Depreciation	2.7	2.9	**2.9**	+1%	+11%

Segment Results(BJPY)		FY2026/3 1H	FY2026/3 2H	FY2027/3 1H	HoH	YoY
SPE	**Orders**	61.3	62.1	**114.1**	+84%	+86%
	Sales	59.4	68.5	**72.6**	+6%	+22%
	OP	12.3	16.1	**17.7**	+10%	+44%
	(OPM)	(20.8%)	(23.5%)	**(24.4%)**	+0.9pt	+3.6pt
Metr.	**Orders**	19.3	20.4	**24.9**	+22%	+29%
	Sales	17.7	21.3	**19.8**	-7%	+12%
	OP	2.4	2.9	**2.6**	-11%	+10%
	(OPM)	(13.5%)	(13.8%)	**(13.3%)**	-0.5pt	-0.2pt

FY2027/3 2Q Quarterly Results

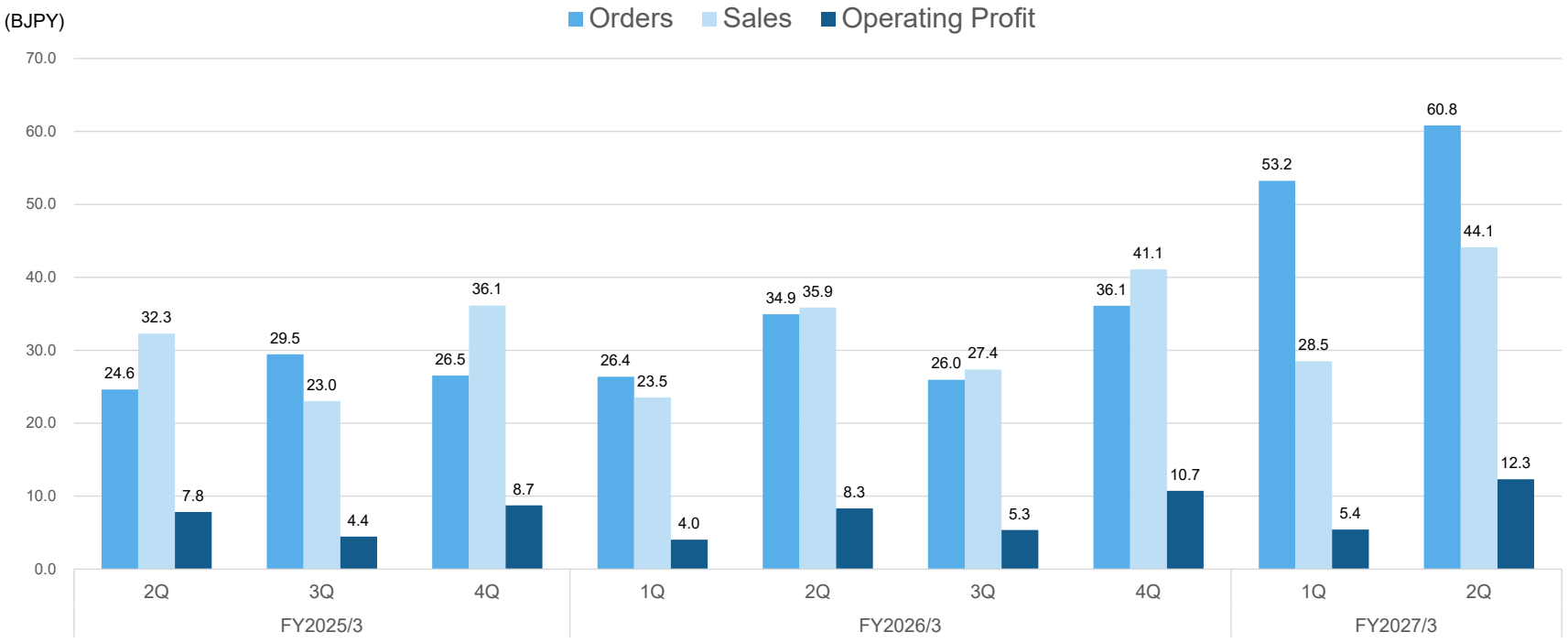
2Q results set a new quarterly record. Sales exceeded the target by approx. ¥4.0B, and the OPM also improved

Company-Wide results (BJPY)	FY2026/3 1Q	2Q	3Q	4Q	FY2027/3 1Q	2Q	QoQ	YoY
Orders	35.9	44.7	36.6	45.8	65.8	73.1	+11%	+64%
Sales	30.9	46.2	35.9	53.9	36.7	55.7	+52%	+21%
Operating profit (OP)	4.6	10.1	6.2	12.8	5.9	14.4	+144%	+42%
(OP Margin) (OPM)	(14.8%)	(21.9%)	(17.3%)	(23.8%)	(16.1%)	(25.9%)	+9.8pt	+4.0pt
Recurring profit	4.5	10.5	6.7	13.1	6.4	14.7	+129%	+40%
Net profit	3.2	6.4	4.5	10.6	4.7	10.8	+132%	+70%
R&D	2.5	3.0	2.9	3.6	3.3	3.4	+3%	+13%
Capex	2.5	4.4	1.5	2.7	1.9	2.8	+43%	-37%
Depreciation	1.2	1.4	1.4	1.6	1.4	1.5	+5%	+5%

Segment Results		1Q	2Q	3Q	4Q	1Q	2Q	QoQ	YoY
SPE	Orders	26.4	34.9	26.0	36.1	53.2	60.8	+14%	+74%
	Sales	23.5	35.9	27.4	41.1	28.5	44.1	+55%	+23%
	OP	4.0	8.3	5.3	10.7	5.4	12.3	+128%	+48%
	(OPM)	(17.1%)	(23.1%)	(19.5%)	(26.1%)	(19.0%)	(27.9%)	+8.9pt	+4.8pt
Metr.	Orders	9.5	9.8	10.7	9.7	12.6	12.3	-2%	+26%
	Sales	7.3	10.3	8.5	12.8	8.2	11.6	+41%	+12%
	OP	0.5	1.8	0.9	2.1	0.5	2.1	+313%	+15%
	(OPM)	(7.5%)	(17.8%)	(10.2%)	(16.3%)	(6.2%)	(18.3%)	+12.0pt	+0.5pt

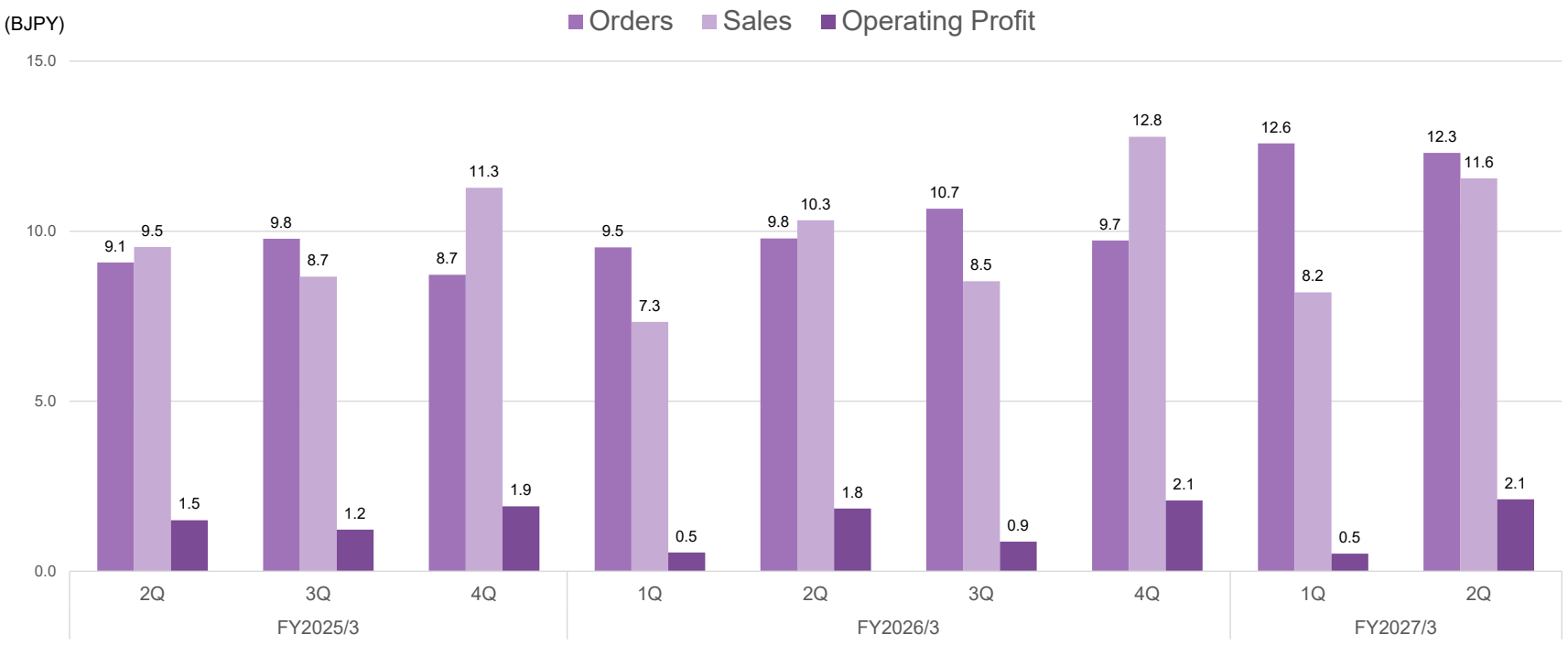
SPE Segment Quarterly Trend

2Q orders were above expectations, driven by continuing HPC business as well as strong demand from China, etc.



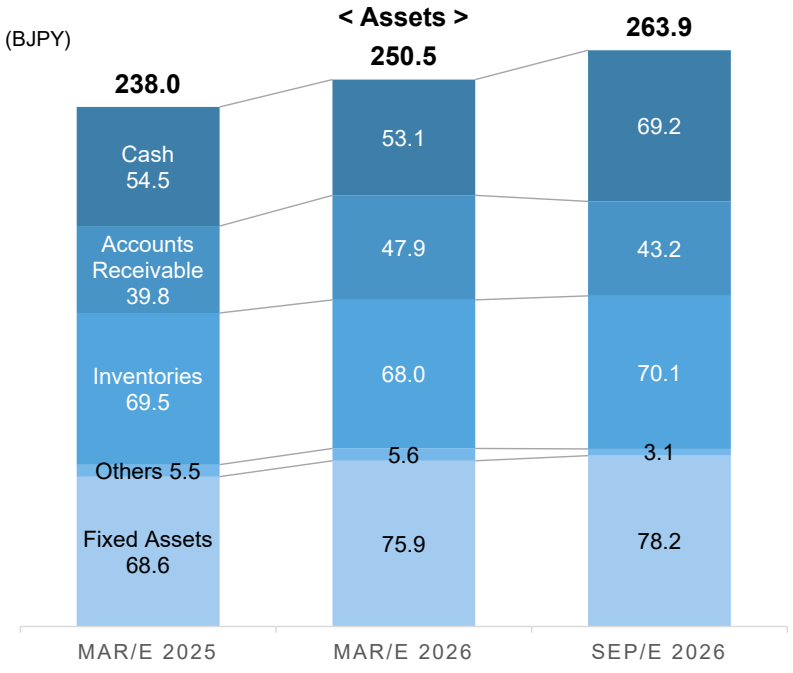
Metrology Segment Quarterly Trend

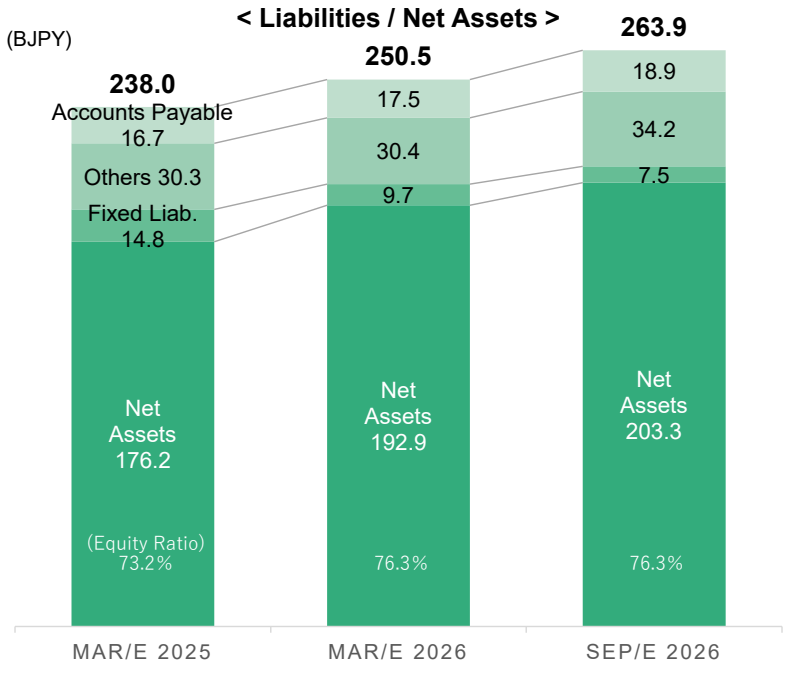
2Q orders at a high level thanks to additional investments for HV production, AI data centers, robots, and others



Balance Sheet

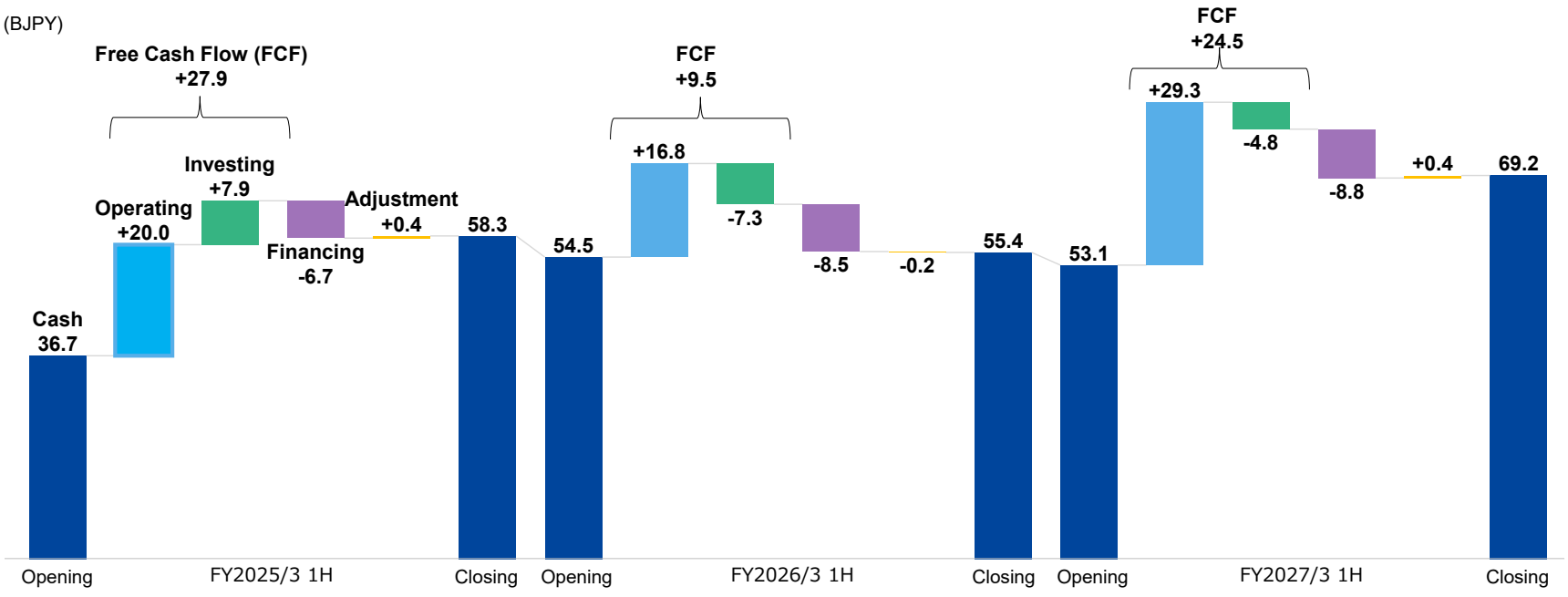
Cash and cash equivalents, inventories, and fixed assets increased compared to Mar/E





Cash Flows

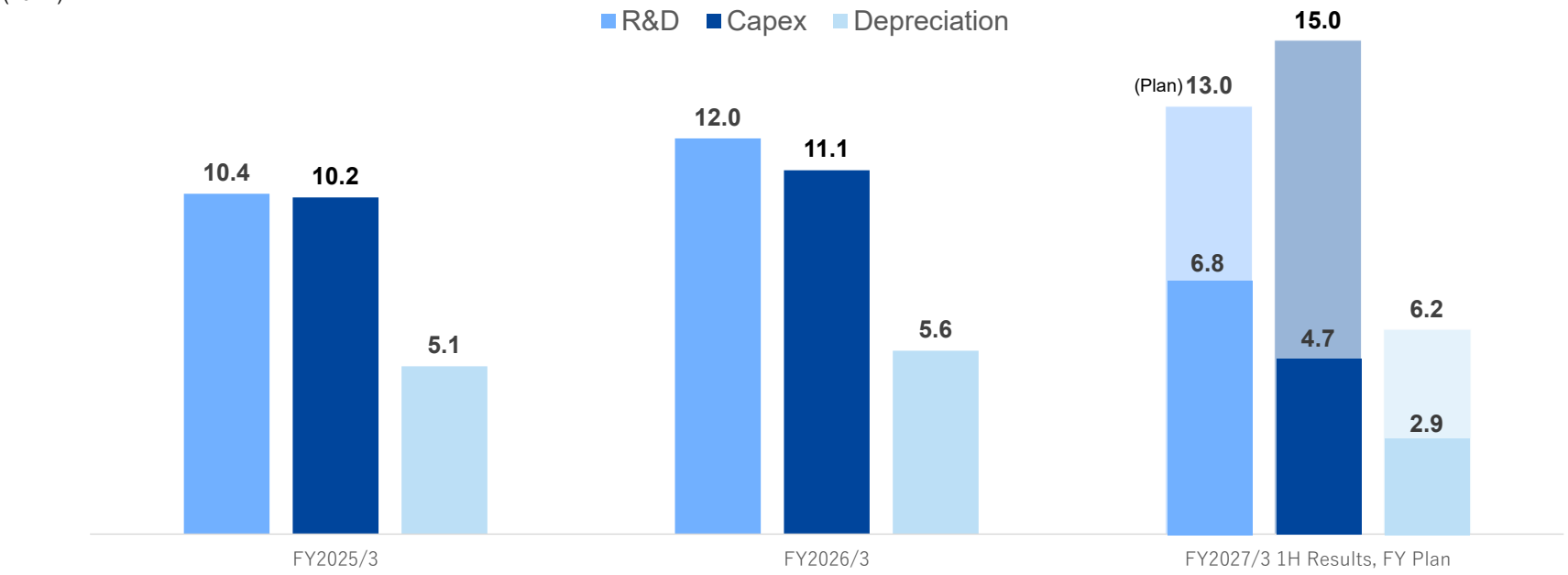
Resulted positive free cash flow owing to profit



R&D, Capex and Depreciation

FY Plan for FY2027/3 remains unchanged

(BJPY)



Premises of FY2027/3 Forecast (Blue: changed by November)

Sales & Profits

SPE： Revised FY forecast after considering 1H results, production trends, and component procurement

- HPC-related including Gen.AI： Sales/profits contribution to rise
- Global OSAT：Growth is seen not only in HPC but also in conventional logic devices
- China Demands：Maintain firm demand driven by high-end use
- Memory (Non-HBM)：Shipments for DRAM/NAND to increase

Metr.： Increase YoY amid recover in industry, price revision, and businesses among aerospace, defense and semis
Profits：Although pressures from an increase of various costs including from a manufacturing volume increase remain, meeting OP target set in the MTP is now expected

Order Trend

SPE： Order trends to remain very strong in 2H FY2027/3 expect FY orders to total approx. ¥220.0B (YoY +80%)

- HPC-related including Gen.AI : Expect very strong trend to continue
- Global OSAT： Demand related to conventional logic devices related will keep strong tone
- China Demands： Solid demand remains mainly for high-end use
- Memory (Non-HBM)： Expect acceleration toward DRAM/NAND investments

Metr.：Expect increasing opportunities among in aerospace, defense, AI infrastructures, semis, and from subsidy-related business

FY2027/3 Forecast

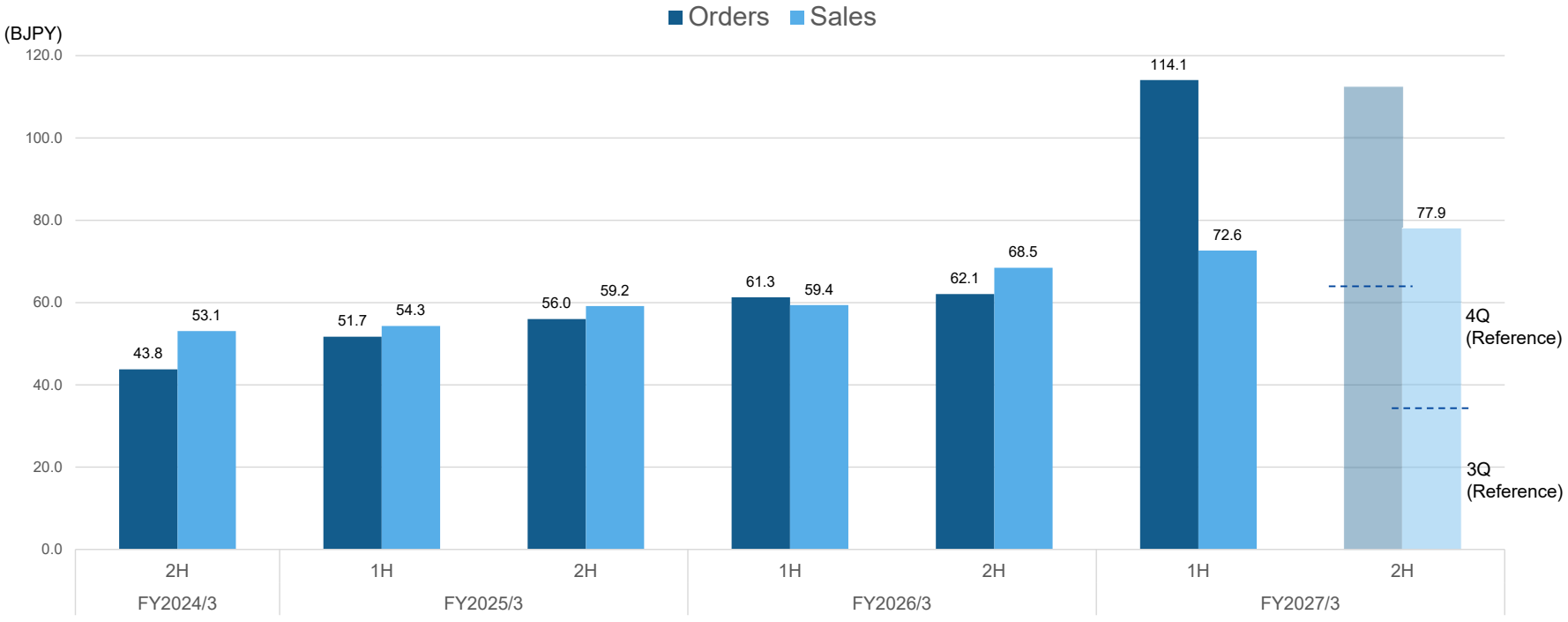
The forecast disclosed on Aug 4th, 2026, has been revised (upward revision for SPE)
Forex assumption remains unchanged : ¥150 / US$ (Forex impact is minimal: High ratio of Yen-based businesses)
Per share dividend projection has also been updated following forecast revision

Company-Wide results (BJPY)	FY2026/3 1H	2H	Full Year	FY2027/3 1H	2H(f)	Full Year	Changes	YoY
Orders	80.6	82.5	163.1	139.0	-	-	-	-
Sales	77.1	89.8	166.8	92.4	**99.6**	**192.0**	+3.0	+15%
Operating profit	14.7	19.0	33.7	20.3	**24.7**	**45.0**	+1.0	+33%
(OP Margin)	(19.1%)	(21.2%)	(20.2%)	(22.0%)	**(24.8%)**	**(23.4%)**	+0.2pt	+3.2pt
Recurring profit	15.0	19.9	34.8	21.1	**24.4**	**45.5**	+1.5	+31%
Net profit	9.6	15.1	24.7	15.5	**16.5**	**32.0**	+1.2	+29%
R&D	5.5	6.5	12.0	6.8	**6.2**	**13.0**	±0.0	+8%
Capex	6.9	4.2	11.1	4.7	**10.3**	**15.0**	±0.0	+36%
Depreciation	2.7	2.9	5.6	2.9	**3.3**	**6.2**	±0.0	+11%

Segment Sales	FY2026/3 1H	2H	Full Year	FY2027/3 1H	2H(f)	Full Year	Changes	YoY
SPE	59.4	68.5	127.9	72.6	**77.9**	**150.5**	+3.0	+18%
Metr.	17.7	21.3	39.0	19.8	**21.7**	**41.5**	±0.0	+7%
Dividend per share (JPY)	111	151	262	158	**158**	**316**	+12	+54

SPE Sales/Orders incl. Forecasts

Anticipate that order levels for the 2H FY2027/3 will remain high (on the same level with the 1H)



Metrology Sales/Orders incl. Forecasts

Estimate 2H orders to decline HoH owing to typical seasonal patterns (FY order likely to increase by 10% YoY)



Outlook for FY2028/3 and beyond

SPE

- The expansion of the Company's TAM will continue until at least CY2028 (Assume +20% CAGR for the probers market)
- Aim to double our prober manufacturing capacity by mid-FY2029/3 compared to the 1H FY2027/3 through:
  - + low-30% in FY2027/3 ; upon expansion of production space at the *Hanno* Plant (Phase 1) (previous estimate: 20%)
  - + mid-20% in FY2028/3 ; upon expansion of production space at the *Hanno* Plant (Phase 2)
  - + mid-20% in FY2029/3 ; upon completion of the *Hanno* No.2 Plant construction (Phase 1)
- Meanwhile, risks related to component procurement require close monitoring

Metrology

- On top of additional investments related to HV production, demand will grow in the aerospace and defense sectors.
- Sectors related to AI data centers (including infrastructure) and robotics for automation and labor-saving initiatives will continue to perform well
- The manufacturing market, driven primarily by outside-of-Japan demand, will continues expand

Mid-term Business Plan(MTP)

- Aim to launch a new MTP starting in FY2028/3, if the Company will achieve our current MTP target during FY2027/3
- The Company currently reviews period, quantitative targets, and others

質疑応答 / Q&A

Supplementary Data - 生成AIを含むHPC / HPC-related business incl. Gen.AI

<売上高/Sales>

(前半期比増減率 / HoH Changes)	2025年度下期 FY2026/3 2H	2026年度上期 FY2027/3 1H	2026年度下期予 FY2027/3 2H (f)
生成AIを含むHPC 全体 HPC-related incl. Gen. AI	前半期比 +32% HoH	前半期比 +48% HoH	前半期比 -5% HoH
うちロジック (生成AIを含む) of which Logic (incl. Gen AI)	前半期比 +11% HoH	前半期比 +105% HoH	前半期比 -3% HoH
うちHBM of which HBM	前半期比 +64% HoH	前半期比 -8% HoH	前半期比 -12% HoH
SPE売上高に占めるHPC関連の割合 HPC-related proportion of total SPE sales	30%半ば / Mid-30%	50%	40%半ば / Mid 40%

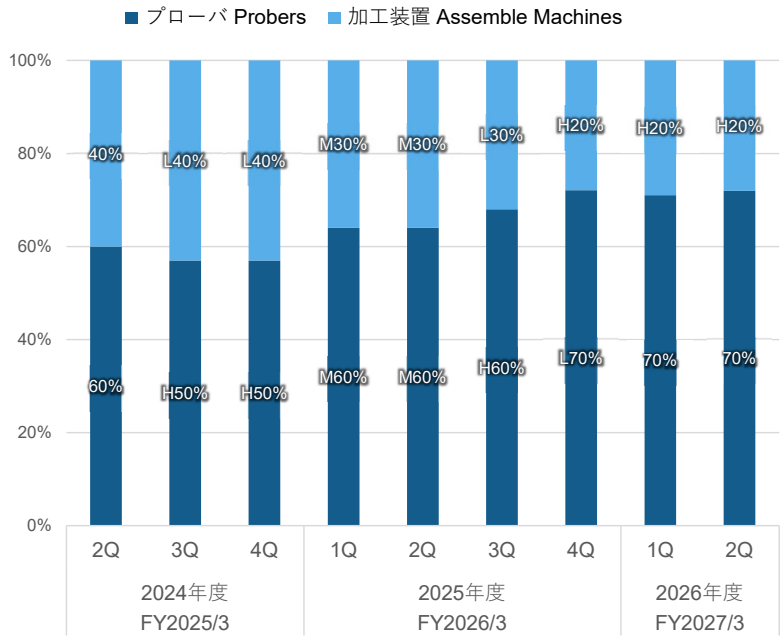
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(前半期比増減率 / HoH Changes)	2025年度下期 FY2026/3 2H	2026年度上期 FY2027/3 1H	2026年度下期予 FY2027/3 2H (f)
生成AIを含むHPC 全体 HPC-related incl. Gen. AI	前半期比 +4% HoH	前半期比 +90% HoH	前半期比 +6% HoH
うちロジック (生成AIを含む) (*) of which Logic (incl. Gen AI) (*)	前半期比 +84% HoH	前半期比 +83% HoH	前半期比 +3% HoH
うちHBM of which HBM	前半期比 -48% HoH	前半期比 +105% HoH	前半期比 +12% HoH
SPE受注高に占めるHPC関連の割合 HPC-related proportion of total SPE orders	40%	40%	40%半ば / Mid 40%

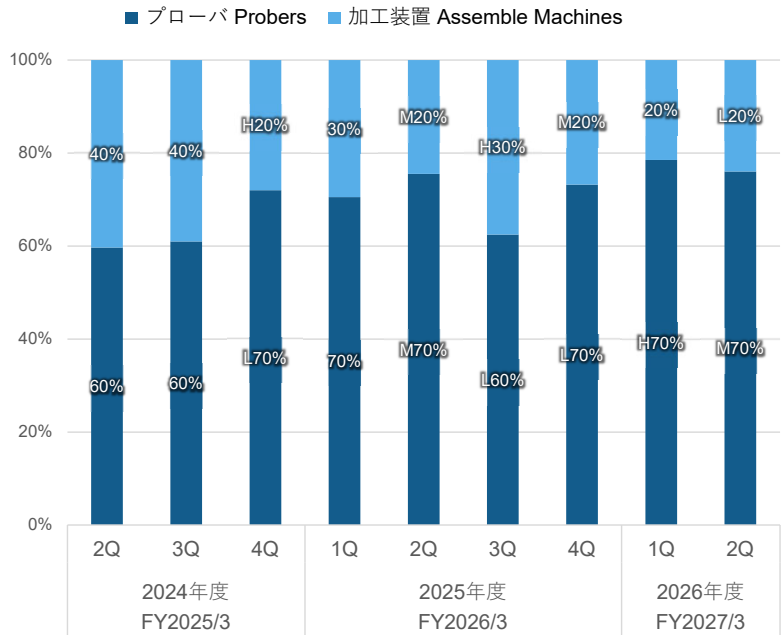
- 変動が大きいため、四半期別の開示は行っておりません。 Due to significant volatilities, the Company does not provide quarterly forecasts.
- 『生成AIを含むHPC全体』は、「うちロジック(生成AIを含む)」および「うちHBM」の合計です。「うちロジック(生成AIを含む)」には、ロジックデバイス向けプローバやAIパッケージング向けの加工装置の需要が含まれています。なお、当社は製品の特性上、検査や加工がおこなわれる半導体デバイスの種別を特定することが困難であることから、生成AIに限定した分類は行っておりません。“HPC-related incl. Gen.AI” represents the sum of ‘of which Logic (incl. Gen.AI)' and ‘of which HBM’. The ‘of which Logic (incl. Gen. AI)' encompasses businesses for probers for logic devices and assembly equipment for AI packaging. Note that due to the nature of our products, it is difficult to identify the specific types of semiconductor devices undergoing inspection or processing; consequently, the Company does not undertake classification limited solely to Generative AI.

Supplementary Data - 製品別構成比 半導体 / SPE Segment per Product

<売上高　Sales>



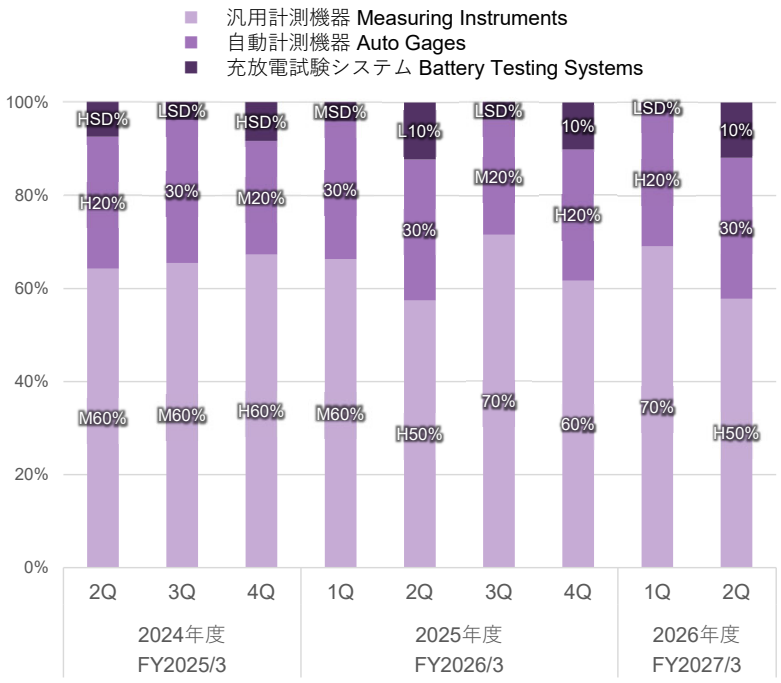
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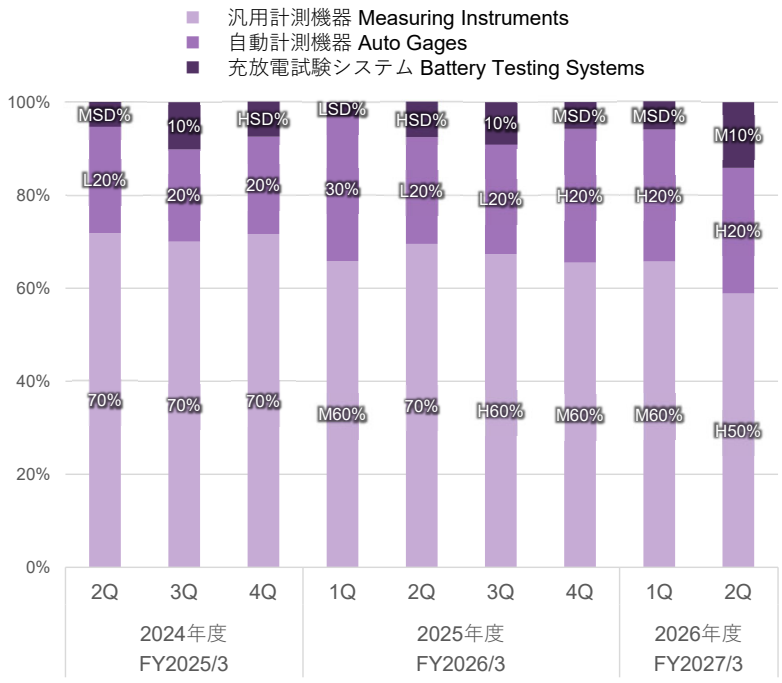
備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD%：一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - 製品別構成比 計測 / Metrology Segment per Product

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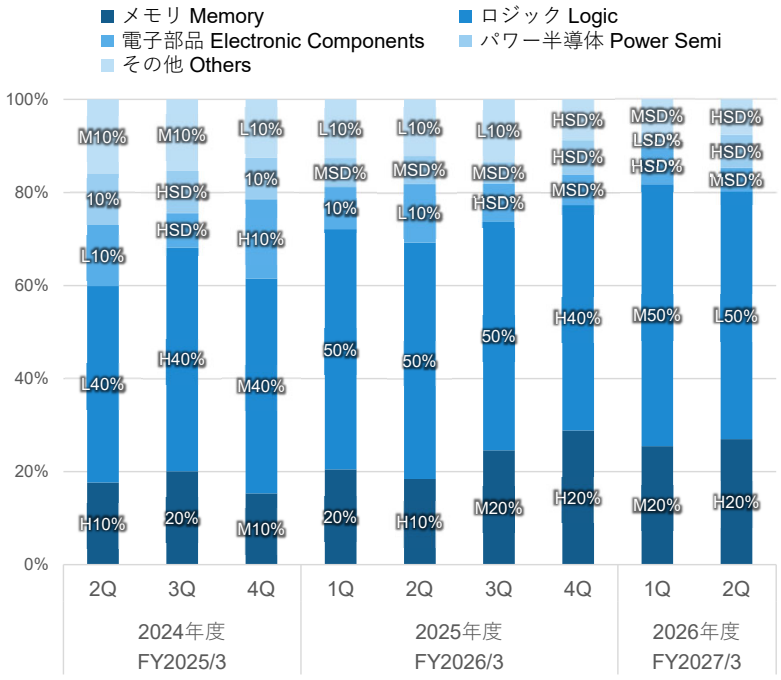
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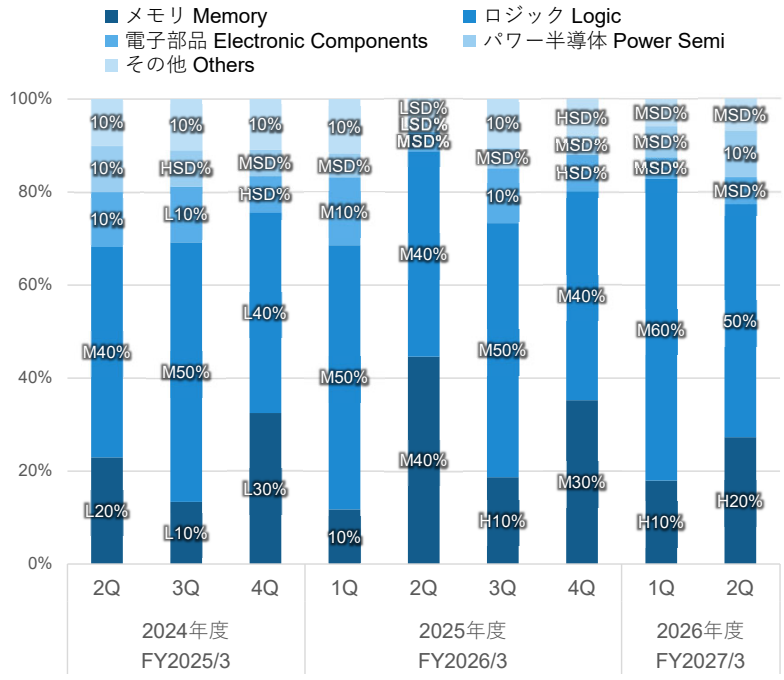
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Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - アプリ別構成比 半導体 / SPE Segment per Application

<売上高　Sales>



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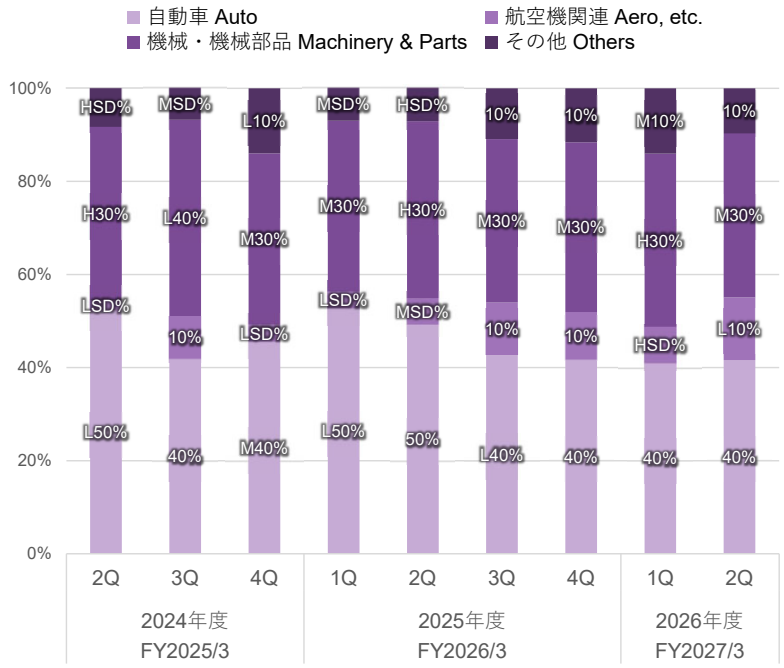


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Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

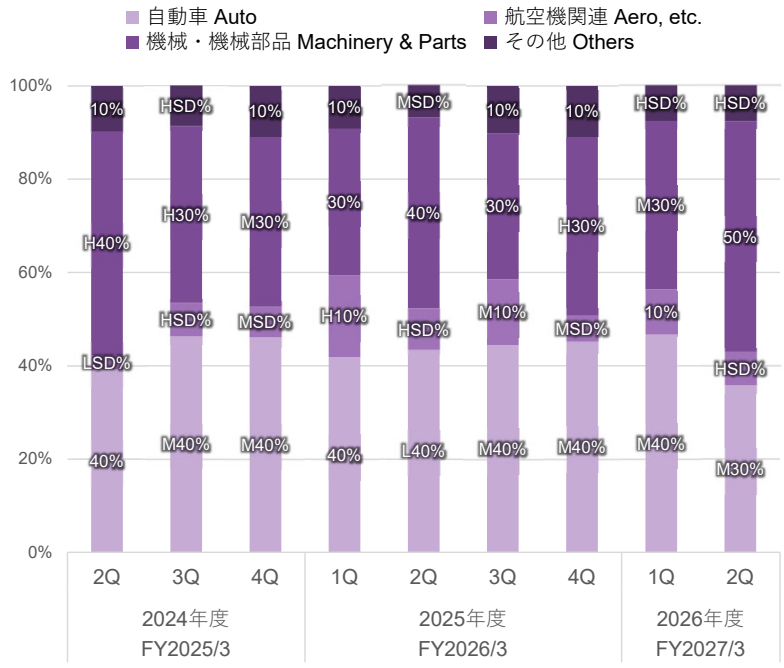
注) 2026年8月4日に開示した構成比データ(売上高、左側)に誤りがありましたので訂正しております。
Note: We have corrected the composition data (sales, left side) disclosed on August 4, 2026, as it contained an error.

Supplementary Data - アプリ別構成比 計測 / Metrology Segment per Application

<売上高　Sales>



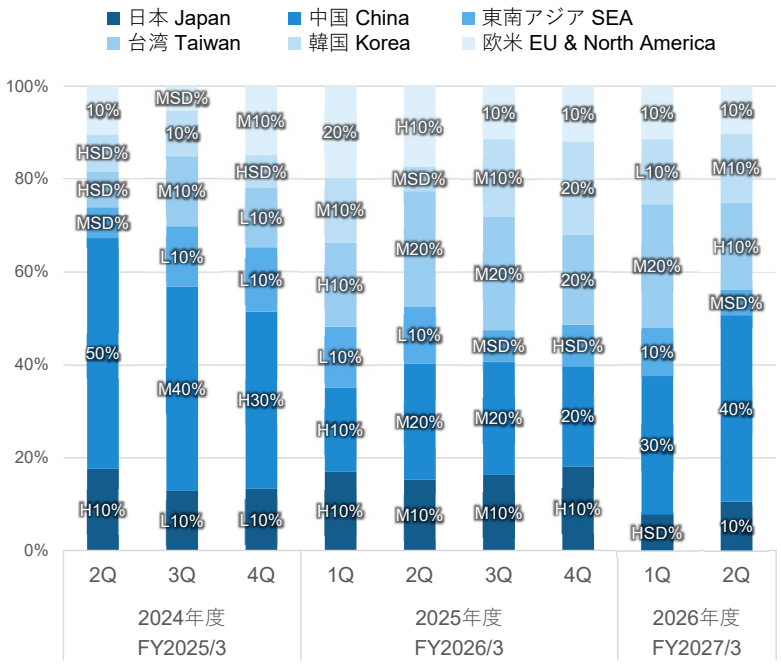
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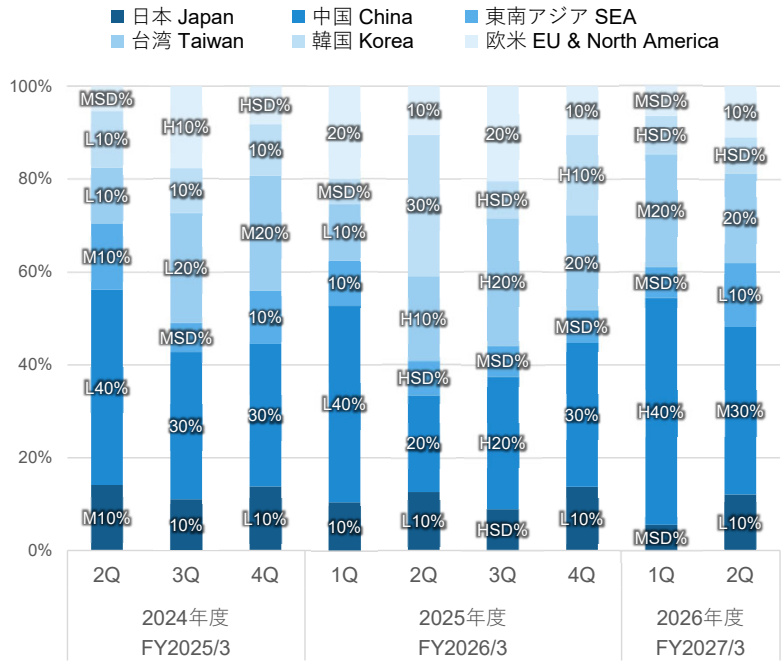
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Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - 地域別構成比 半導体 / SPE per Region

<売上高　Sales>



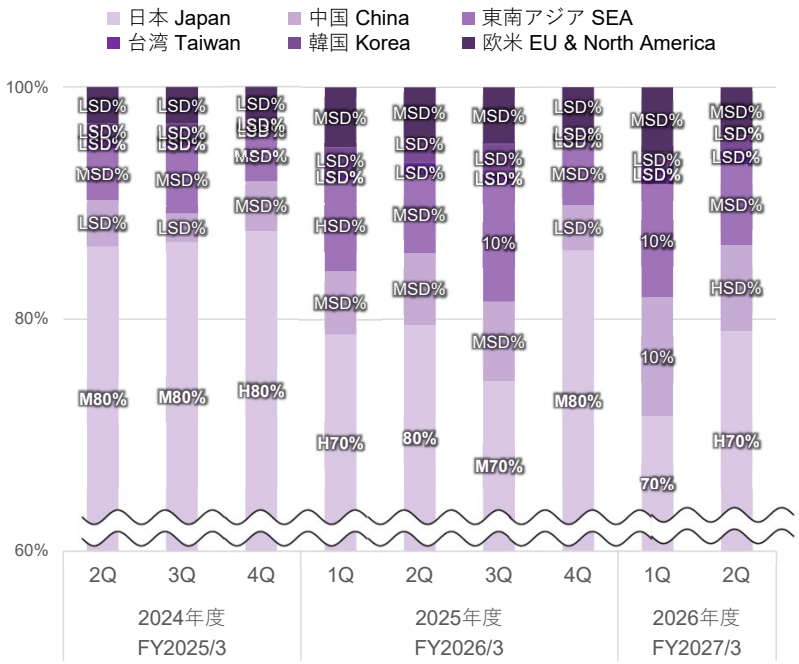
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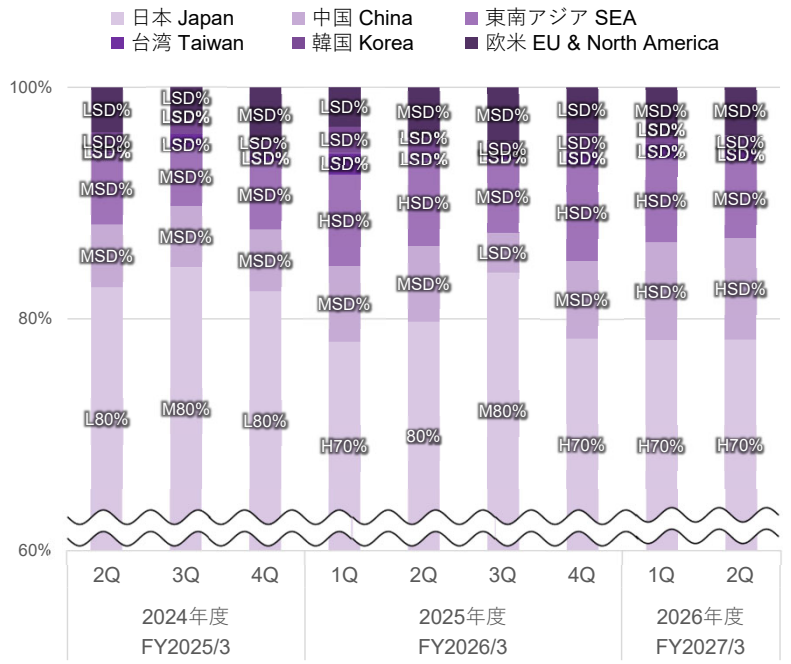
備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD%：一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。
Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - 地域別構成比 計測 / Metrology per Region

<売上高　Sales>



<受注高　Orders>



備考：取引顧客の国籍による分類であり、日本向け売上高・受注高には第3国への輸出案件が含まれています。This data classifies based on customers' nationality. Sales and orders for Japan include export transactions to third countries.

備考：表中の記載は、L:Low(前半), M:Middle(半ば), H:High(後半)を、LSD% ：一桁%前半 (0-3%) 、MSD% :一桁%半ば (4-6%)、HSD%:一桁%後半 (7-9%)を示します。内訳の合計が100%にならない場合があります。

Note: The entries in the table represent L: Low, M: Middle, and H: High; LSD%: Low Single Digit % (0-3%), MSD%: Mid Single Digit % (4–6%), and HSD%: High Single Digit % (7–9%), respectively. SUM may not equal 100%.

Supplementary Data - セグメント別業績推移 / Segment

(百万円) Million Yen		連結会計期間 Consolidated Fiscal Year				四半期 Quarterly							
		2023年 3月期 FY2023/3	2024年 3月期 FY2024/3	2025年 3月期 FY2025/3	2026年 3月期 FY2026/3	2026年3月期 FY2026/3				2027年3月期 FY2027/3			
						1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
受注高 Orders	半導体 SPE	99,366	86,082	107,713	123,396	26,378	34,945	25,965	36,106	53,236	60,837		
	計測 Metr.	36,960	34,802	37,917	39,700	9,523	9,786	10,661	9,728	12,583	12,302		
	合計 Total	136,326	120,885	145,631	163,096	35,901	44,732	36,627	45,835	65,820	73,140		
受注残高 Backlog	半導体 SPE	89,371	75,398	69,630	65,149	72,466	71,541	70,134	65,149	89,870	106,577		
	計測 Metr.	12,428	12,606	13,470	14,210	15,660	15,123	17,257	14,210	18,592	19,343		
	合計 Total	101,799	88,004	83,101	79,359	88,127	86,664	87,391	79,359	108,463	125,921		
売上高 Sales	半導体 SPE	112,365	100,055	113,481	127,878	23,542	35,870	27,372	41,092	28,515	44,130		
	計測 Metr.	34,436	34,624	37,053	38,960	7,333	10,323	8,528	12,775	8,201	11,552		
	合計 Total	146,801	134,680	150,534	166,839	30,876	46,194	35,900	53,867	36,716	55,682		
営業利益 OP	半導体 SPE	29,866	19,899	24,311	28,404	4,031	8,297	5,347	10,727	5,409	12,308		
	計測 Metr.	4,628	5,408	5,392	5,333	549	1,838	867	2,077	511	2,112		
	合計 Total	34,494	25,307	29,703	33,738	4,581	10,136	6,214	12,805	5,920	14,420		
営業利益率 OP Margin	半導体 SPE	26.6%	19.9%	21.4%	22.2%	17.1%	23.1%	19.5%	26.1%	19.0%	27.9%		
	計測 Metr.	13.4%	15.6%	14.6%	13.7%	7.5%	17.8%	10.2%	16.3%	6.2%	18.3%		
	合計 Total	23.5%	18.8%	19.7%	20.2%	14.8%	21.9%	17.3%	23.8%	16.1%	25.9%		

Supplementary Data - 損益計算書 / Income Statement

(百万円 (EPS除く)) Million Yen(excl. EPS)	連結会計期間 Consolidated Fiscal Year				四半期 Quarterly							
					2026年3月期 FY2026/3				2027年3月期 FY2027/3			
	2023年3月期 FY2023/3	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	1Q	2Q	3Q	4Q	1Q	2Q	3Q	4Q
売上高 Net Sales	146,801	134,680	150,534	166,839	30,876	46,194	35,900	53,867	36,716	55,682		
売上原価 Cost of goods sold	84,967	79,917	88,081	97,978	18,468	27,411	21,063	31,034	21,316	31,579		
売上総利益 Gross Profit on Sales	61,834	54,762	62,453	68,860	12,407	18,783	14,837	22,832	15,400	24,102		
販売費および一般管理費 Selling, general and administrative expenses	27,339	29,454	32,750	35,122	7,825	8,647	8,622	10,026	9,479	9,681		
営業利益 Operating profit	34,494	25,307	29,703	33,738	4,581	10,136	6,214	12,805	5,920	14,420		
営業外収益 Non-operating income	965	1,404	921	1,481	133	309	609	428	576	385		
営業外費用 Non-operating expenses	162	259	684	394	252	-69	84	126	66	90		
経常利益 Recurring Profit	35,297	26,453	29,939	34,825	4,462	10,515	6,739	13,108	6,430	14,715		
特別利益 Extraordinary gains	103	824	4,493	194	3	85	105	0	3	126		
特別損失 Extraordinary losses	2,099	21	158	1,833	-	2,103	-	-269	-	-		
税金等調整前当期/四半期純利益 Profit before income taxes and minority interests	33,301	27,255	34,275	33,186	4,465	8,498	6,844	13,377	6,434	16,540		
法人税等合計 Total Income tax and others	9,607	7,791	8,531	8,354	1,228	2,090	2,268	2,768	1,698	4,006		
非支配株主に帰属する当期/四半期純利益 Net Profit attributable to minority interests	62	84	106	92	7	25	39	18	67	13		
親会社株主に帰属する当期/四半期純利益 Net Profit attributable to Owners of the Parent	23,630	19,378	25,637	24,739	3,229	6,382	4,536	10,590	4,667	10,821		
1株当たり当期/四半期純利益(円) Net Profit per Share(Yen)	581.33	480.49	633.75	610.02	79.77	157.32	112.74	260.73	115.01	266.61		
潜在株式調整後 1株当たり当期/四半期純利益(円) Net Profit per Share(diluted)(Yen)	575.62	475.42	628.31	606.14	-	-	-	-	-	-		

Supplementary Data - 貸借対照表 / Balance Sheet

(百万円)(Million Yen)		2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期 中間期 FY2027/3 Interim
流動資産 Current Assets	現金及び預金 Cash and cash equivalents	36,782	54,541	53,073	69,219
	売上債権※1 Accounts Receivable※1	42,801	39,809	47,877	43,229
	棚卸資産 Inventories	67,225	69,513	68,022	70,125
	その他 Others	7,022	5,477	5,634	3,106
	合計 Total	153,831	169,341	174,607	185,680
固定資産合計 Total Fixed Assets		71,693	68,610	75,925	78,228
総資産 Total Assets		225,524	237,952	250,533	263,909
流動負債 Current Liabilities	買入債務※2 Accounts Payable※2	17,845	16,665	17,529	18,898
	その他 Others	28,156	30,268	30,350	34,245
	合計 Total	46,002	46,933	47,879	53,144
固定負債合計 Total long-term liabilities		21,094	14,789	9,737	7,478
負債合計 Total Liabilities		67,097	61,723	57,617	60,623
純資産合計 Total Net Assets		158,427	176,229	192,916	203,285
負債・純資産合計 Total Liabilities and Net Assets		225,524	237,952	250,533	263,909
有利子負債合計 Total interest-bearing debt		25,171	20,084	14,713	12,190
自己資本比率 Equity Ratio(%)		69.4%	73.2%	76.3%	76.3%
自己資本利益率 ROE(%)		12.9%	15.5%	13.5%	13.6%

※1: 電子記録債権、契約資産を含みます。 Incl. Electronically recorded monetary claims.
※2: 電子記録債務を含みます。 Incl. Electronically recorded obligations-operating.

Supplementary Data - 各種費用, キャッシュフロー/ Expenses and

(百万円)(Million Yen)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期中間期 FY2027/3 Interim
研究開発費　R&D expenses	9,042	10,354	12,037	6,769
設備投資　Capex	11,602	10,245	11,069	4,696
減価償却費（のれんの償却を除く） Depreciation（excl. Amortization of goodwill）	4,673	5,105	5,582	2,940

(百万円)(Million Yen)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期 中間期 FY2027/3 Interim
営業活動によるキャッシュフロー Cash flows from operating activities	4,892	28,824	25,012	29,338
投資活動によるキャッシュフロー Cash flows from investing activities	-10,563	2,541	-11,491	-4,827
フリーキャッシュフロー Free cash flows	-5,671	31,365	13,520	24,511
財務活動によるキャッシュフロー Cash flows from financing activities	1,616	-13,991	-15,674	-8,797
現金及び現金同等物に係る換算差額等 Adjustments	755	404	689	432
現金及び現金同等物の期末残高 Cash and cash equivalents at the end of year	36,736	54,516	53,052	69,198

(従業員) (# of Employees)	2024年3月期 FY2024/3	2025年3月期 FY2025/3	2026年3月期 FY2026/3	2027年3月期中間期 FY2027/3 Interim
正社員合計　Total full-time employees	2,658	2,767	2,890	2,994
期間平均臨時従業員数 (外書) Average number of part-time employees, not included in the above figure	1,225	1,258	1,365	1,394
従業員合計 (※1)　Number of employees	3,883	4,025	4,255	4,388

※1: 従業員合計は、正社員合計人数と、期間平均臨時従業員数の単純合算です。“Number of employees” is a simple sum of the total number of regular employees and the average number of temporary employees during the period.